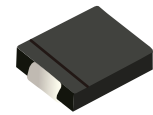
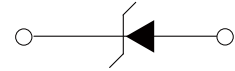


FEATURES

- | Low profile package
- | Idea for printed circuit board
- | Glass passivated Junction chip
- | High forward surge current capability
- | Low reverse leakage



DO-214AB(SMC)



Schematic Symbol

MECHANICAL DATA

- | Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- | Moisture Sensitivity: Level 1 per J-STD-020
- | Polarity: Cathode line denotes the cathode end

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS AND CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	GS8AC	GS8BC	GS8DC	GS8GC	GS8JC	GS8KC	GS8MC	Unit	
Marking		GS8AC	GS8BC	GS8DC	GS8GC	GS8JC	GS8KC	GS8MC		
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000		
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V	
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000		
Maximum average forward rectified current at T _L =100°C	I _{F(AV)}	8.0								A
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load per diode	I _{FSM}	175.0								
Maximum instantaneous forward voltage at 8.0A	V _F	1.0								V
Maximum reverse current @ rated V _R	T _J =25°C	2.0								uA
	T _J =125°C	200								
Typical junction capacitance (Note1)	C _J	60.0								pF
Typical thermal resistance	R _{θJA}	47.0								°C/W
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150								°C

Note 1: Measured at 1MHz and applied reverse voltage of 4.0V D.C.

CHARACTERISTIC CURVES

Fig. 1- Derating Curve Output Rectified Current

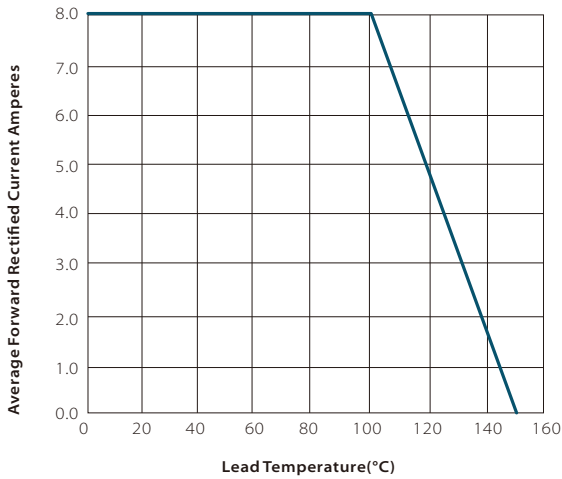


Fig. 2-maximum Non-repetitive Peak Forward Surge Current Perleg

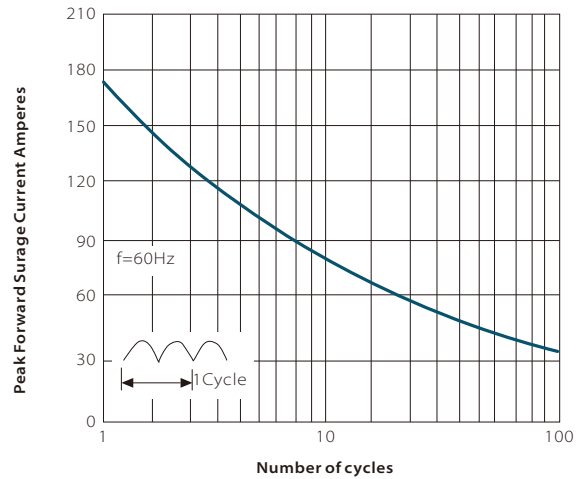


Fig. 3-Typical Forward Voltage Characteristics

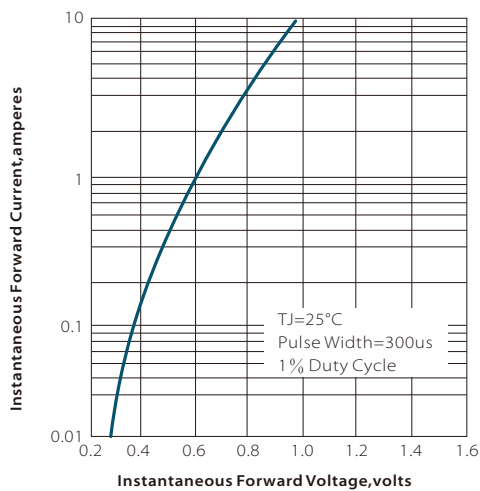
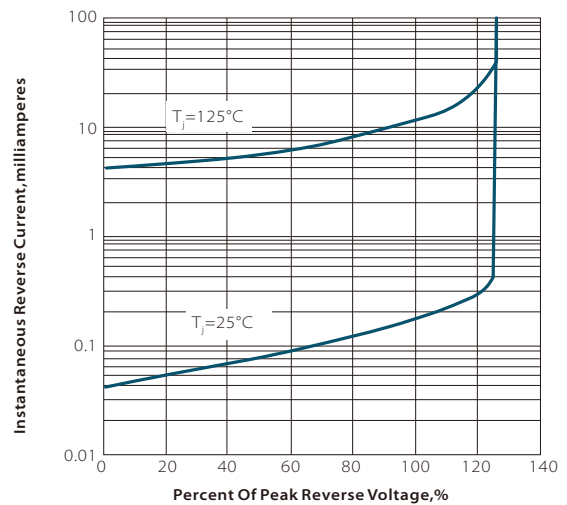
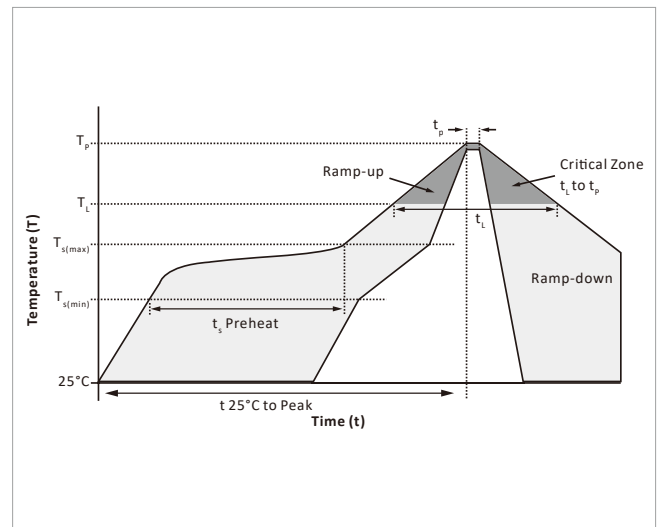


Fig. 4-Typical Reverse Leakage Characteristics

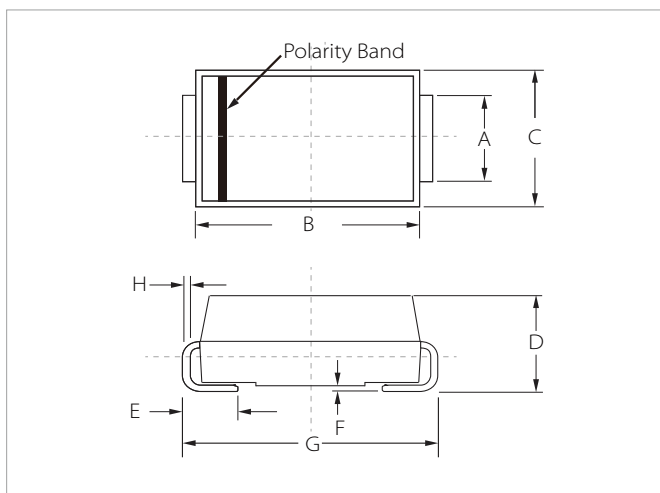


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_p)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

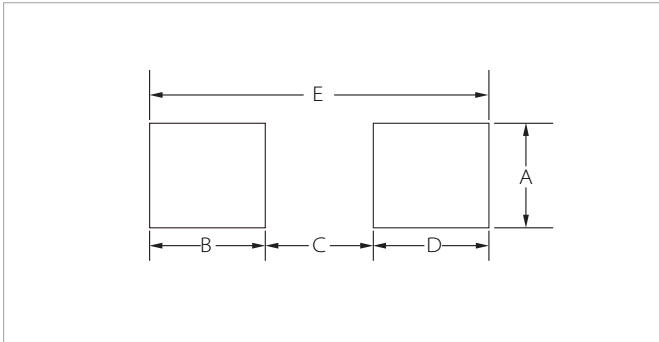


DO-214AB(SMC) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.80	3.20	0.110	0.126
B	6.60	7.20	0.260	0.283
C	5.70	6.10	0.224	0.240
D	2.15	2.75	0.085	0.108
E	1.00	1.60	0.039	0.063
F	0.02	0.20	0.000	0.008
G	7.60	8.00	0.299	0.315
H	0.15	0.30	0.006	0.012

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	-	0.129	-
B	2.40	-	0.094	-
C	-	4.20	-	0.165
D	2.40	-	0.094	-
E	8.20REF		0.323REF	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
GS8AC-GS8MC	DO-214AB(SMC)	3000PCS	13"

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